



# THCV2911A

V-by-One® HS Redriver with Linear Equalization

## General Description

The THCV2911A is low power, high performance active redriver for V-by-One® HS with data rates up to 4Gbps. The THCV2911A pinout is configured as a forward and sub channels.

The THCV2911A features a powerful 15-stages continuous time linear equalizer (CTLE) to provide a boost of up to +9.3dB at 2GHz and open an input eye that is completely closed due to inter-symbol interference (ISI) induced by the inter-connect mediums such as cable or FR-4.

The programmable settings can be applied via pin configurations which eliminates the needs for an external microprocessor and software driver.

## Features

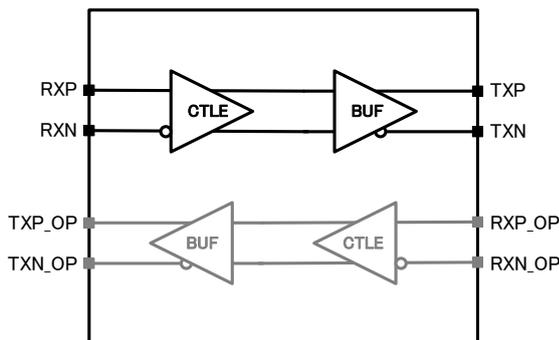
- Signal Conditioning with Linear Equalizer
- A forward and optional lane Redriver for up to 4 Gbps
- Linear Equalization up to +9.3dB@2GHz
- Adjustable Receiver Equalization and DC Gain
- Programmable via Pin Selection
- Flow-Thru Pinout
- Single Supply Voltage (3.3V)
- ESD HBM <math>\pm 4kV</math>
- Package : QFN30 (2.5mm x 4.5mm)
- -40 to 105°C Operating Temperature

## Applications

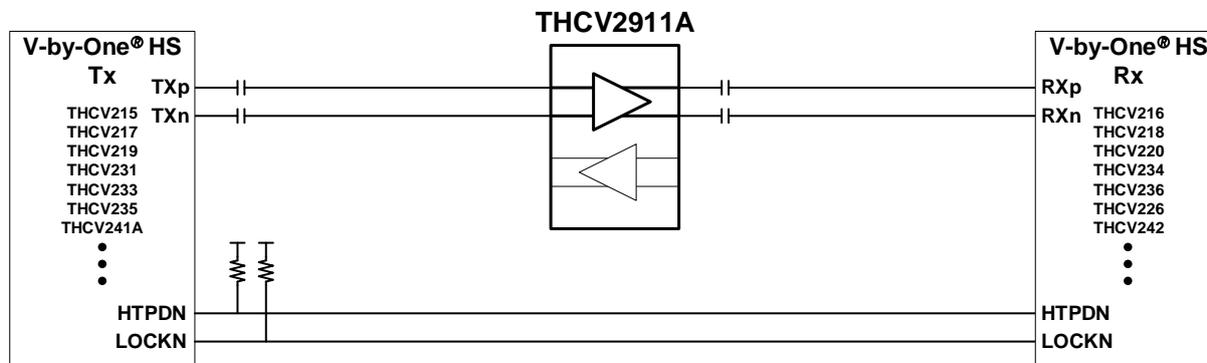
All V-by-One® HS applications for reach extension such as

- Digital Signage
- Digital blackboard
- Multi-Function Printer
- Production Printer
- Medical imaging
- Machine vision
- Image Sensor
- Camera
- Active Cable

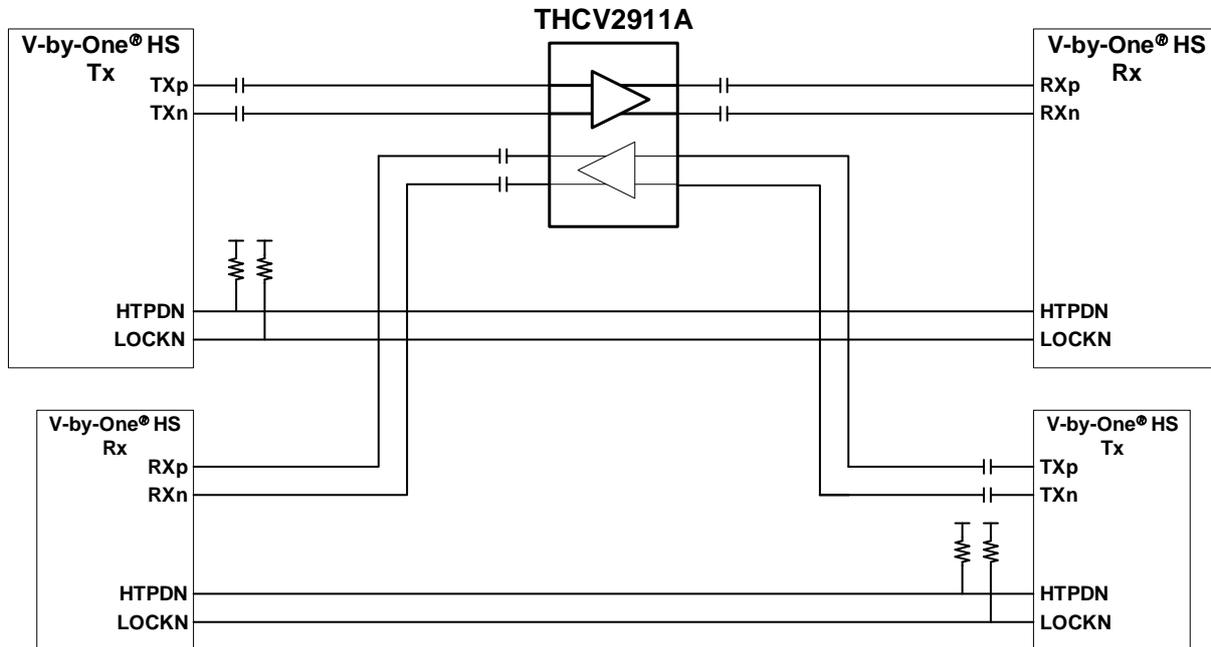
## Block Diagram



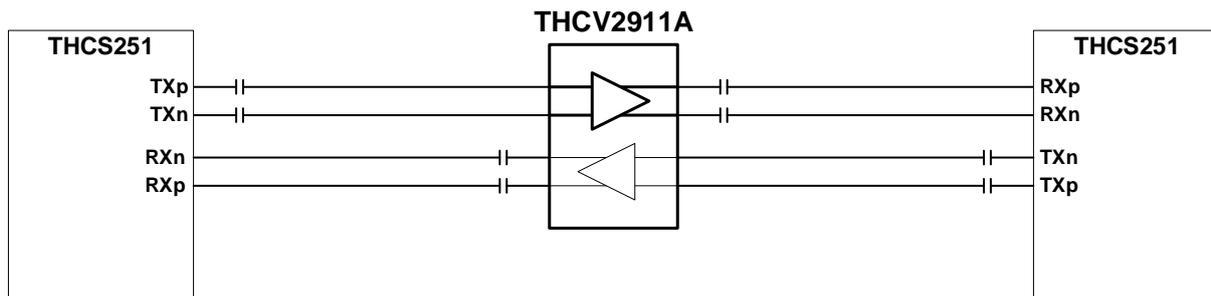
## Typical Application



### Optional Application



### Optional Application with THCS251







**Pin Description**

Pin Name	Pin No	Type	Description
RXP	2	CI	High-Speed CML Signal Input of Main-Lane
RXN	3	CI	High-Speed CML Signal Input of Main-Lane
TXP	24	CO	High-Speed CML Signal Output of Main-Lane
TXN	23	CO	High-Speed CML Signal Output of Main-Lane
RXP_OP	17	CI	High-Speed CML Signal Input of Optional-Lane(OP)
RXN_OP	18	CI	High-Speed CML Signal Input of OP
TXP_OP	9	CO	High-Speed CML Signal Output of OP
TXN_OP	8	CO	High-Speed CML Signal Output of OP
EN	30	I	Channel Enable. With Internal 300kΩ Pull-up Resistor. 0 : Power Down 1 : Normal Operation
EQAC1	26	3LI (*1)	Main Rx Equalizer Peak Gain Setting This pin along with EQAC0 allows for up to 5 settings.
EQAC0	27	3LI (*1)	Main Rx Equalizer Peak Gain Setting This pin along with EQAC1 allows for up to 5 settings.
EQAC1_OP	14	3LI (*1)	OP Rx Equalizer Peak Gain Setting This pin along with EQAC0_OP allows for up to 5 settings.
EQAC0_OP	15	3LI (*1)	OP Rx Equalizer Peak Gain Setting This pin along with EQAC1_OP allows for up to 5 settings.
EQDC	29	3LI (*1)	Main Equalizer DC Gain Setting
EQDC_OP	12	3LI (*1)	OP Equalizer DC Gain Setting
PD_OP	11	3LI (*1)	Chip Operation Mode Select, if EN=1 F : OP Enable, 1 : OP Disable,
VCC	1, 10, 16, 25	PWR	Power Supply Pin for On-chip Regulator.
GND	4,5,6,7,13, 19,20,21, 22,28,31	GND	Ground. Must be tied to the PCB ground plane through an array of vias. Pin#31 is exposed pad ground.

CI: CML Input Buffer, CO: CML Output Buffer  
 I: LVCMOS Input Buffer, 3LI: 3-Level LVCMOS Input Buffer,  
 PWR: Power Supply, GND: Ground

\*1 : 3-Level Input Buffer. With internal 180kΩ pull-up resistor and 300kΩ pull-down resistor.



**Operation Mode Settings**

**Table 1. Operation Mode Settings**

Pin Settings		Operation Mode
EN	PD_OP	
1	0(*1)	Reserved
	F(*2)	OP Enable
	1(*3)	OP Disable
0	Ignore	Chip Power Down.

- \*1 Tie 0Ω to GND
- \*2 Leave pin Open
- \*3 Tie 0Ω to VCC

**Linear Equalizer Settings**

**Table 2. Linear Equalizer Settings**

EQAC1(OP)	EQAC0(OP)	EQDC(OP)	Equalizer Settings (dB)					
			Up to 0.2GHz	@0.5GHz (1Gbps)	@1.0GHz (2Gbps)	@1.5GHz (3Gbps)	@2.0GHz (4Gbps)	
0	*	*	Reserved					
F	0	0	-1.5	-0.8	0.5	1.9	3.0	
F	F			-0.7	1.0	2.7	4.1	
F	1			Reserved				
1	0			-0.6	1.4	3.3	5.0	
1	F			-0.4	1.9	4.2	6.1	
1	1			-0.2	2.3	4.7	6.7	
F	0	F	1.2	1.7	2.7	3.6	4.3	
F	F			1.8	3.2	4.2	5.1	
F	1			Reserved				
1	0			1.9	3.3	4.6	5.8	
1	F			2.0	3.6	5.3	6.7	
1	1			2.1	3.9	5.7	7.2	
F	0	1	4.5	5.2	6.3	7.0	7.4	
F	F			5.2	6.5	7.4	7.9	
F	1			Reserved				
1	0			5.3	6.6	7.6	8.3	
1	F			5.3	6.8	8.0	8.9	
1	1			5.3	7.0	8.3	9.3	

Average of all channels in typical condition



**Absolute Maximum Ratings**

**Table 3. Absolute Maximum Ratings**

Parameter	Min	Typ	Max	Unit
Supply Voltage(VCC)	-0.3	-	4.0	V
LVC MOS Input/Output Voltage	-0.3	-	VCC+0.3	V
3-Level LVC MOS Input Voltage	-0.3	-	VCC+0.3	V
CML Receiver Input Voltage	-0.3	-	VCC+0.3	V
CML Transmitter Output Voltage	-0.3	-	VCC+0.3	V
ESD Rating	HBM	-	±4	kV
	CDM	-	±1000	V
Storage Temperature	-55	-	125	°C
Junction Temperature	-	-	125	°C
Reflow Peak Temperature/Time	-	-	260/10	°C/sec

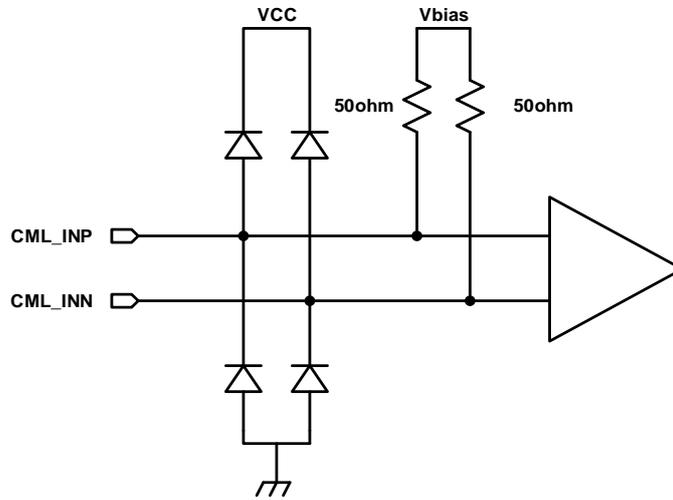
**Recommended Operating Conditions**

**Table 4. Recommended Operating Conditions**

Parameter	Min	Typ	Max	Unit
Supply Voltage(VCC)	3.0	3.3	3.6	V
Supply Ramp Requirement	0.1	-	50	ms
Operating Temperature	-40	-	105 85(*1)	°C

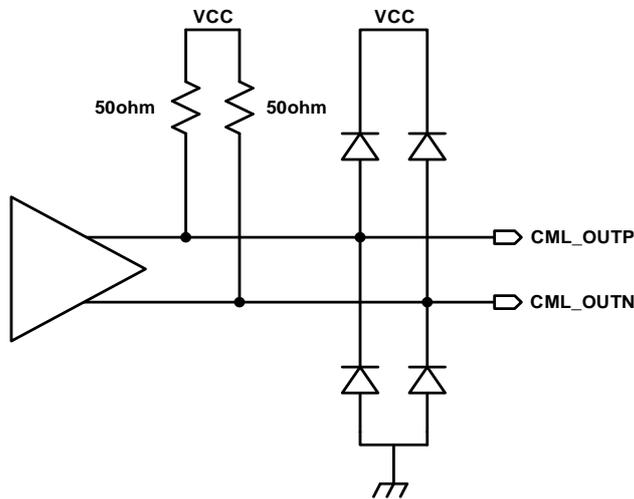
(\*1) PD\_OP=F

**Equivalent CML Input Schematic Diagram**



**Figure 1. CML Input Schematic Diagram**

**Equivalent CML Output Schematic Diagram**



**Figure 2. CML Output Schematic Diagram**

**Equivalent LVC MOS Input Schematic Diagram**

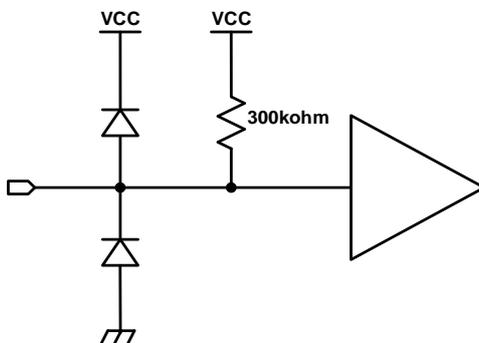


Figure 3. LVC MOS Input Schematics Diagram

**Equivalent 3-Level LVC MOS Input Schematic Diagram**

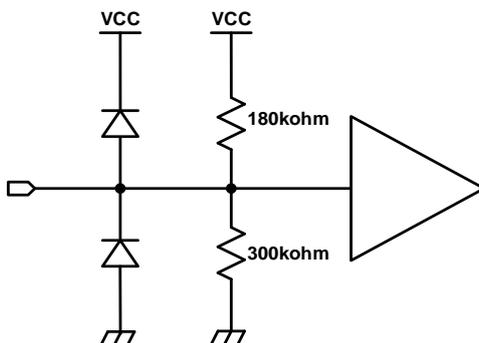


Figure 4. 3-Level Input Schematics Diagram



**Electrical Specification**

Supply Current

**Table 5. Supply Current**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
ICCW	Active Mode Supply Current	PD_OP=1	-	58	84	mA
		PD_OP=F	-	84	106	mA
ICCS	Power Down Supply Current	-	-	120	180	uA

LVC MOS DC Specification

**Table 6. LVC MOS DC Specification**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V <sub>IH</sub>	High Level Input Voltage	-	2.0	-	VCC	V
V <sub>IL</sub>	Low Level Input Voltage	-	0	-	0.7	V

3-Level LVC MOS DC Specification

**Table 7. 3-Level LVC MOS DC Specification**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V <sub>THL</sub>	Low Level Input Voltage	0(*1)	0	-	VCC*0.25 - 0.3	V
V <sub>THF</sub>	F-Level Input Voltage	F(*2)	VCC*0.5 + 0.3	-	VCC*0.75 - 0.3	V
V <sub>THH</sub>	High Level Input Voltage	1(*3)	VCC*0.75 + 0.3	-	VCC	V
I <sub>IH_3L</sub>	High level Input Leak Current	VIN=VCC	-100	-	100	uA
I <sub>IL_3L</sub>	Low Level Input Leak Current	VIN=GND	-100	-	100	uA

## Receiver DC Specification

**Table 8. Receiver DC Specification**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
VRTH	CML Differential Input High Threshold	-	-	-	50	mV
VRTL	CML Differential Input Low Threshold	-	-50	-	-	mV
IRIH	CML Input Leak Current High	EN=0,RXP/N=VCC	-10	-	10	uA
IRIL	CML Input Leak Current Low	EN=0,RXP/N=GND	-10	-	10	uA
RRIN	CML Differential Input Resistance	-	-	100	-	$\Omega$

## Transmitter DC Specifications

**Table 9. Transmitter DC Specification**

Over recommended operating supply and temperature range unless otherwise specified

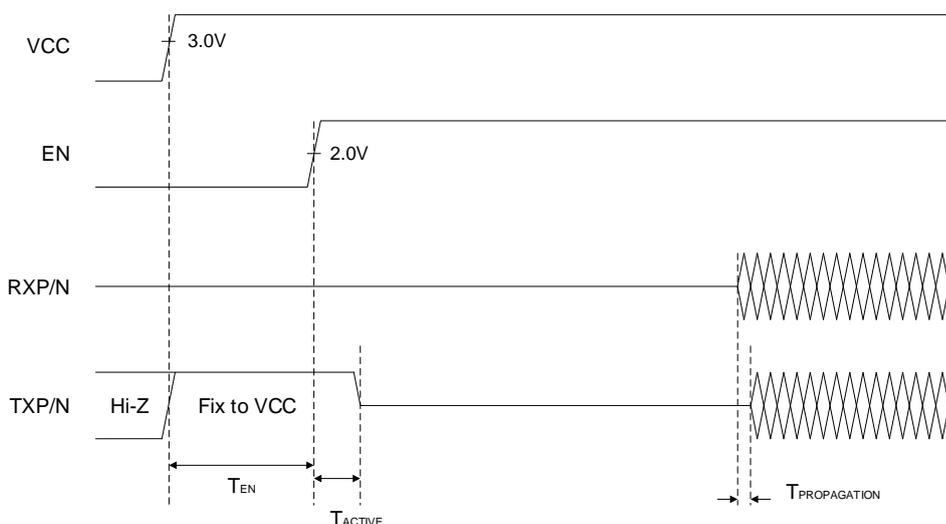
Symbol	Parameter	Condition	Min	Typ	Max	Unit
VTOC	CML Common mode Output Voltage	-	-	VCC-0.75	-	V
ITOH	CML Output Leak Current High	EN=0	-	-	50	uA

AC Specifications

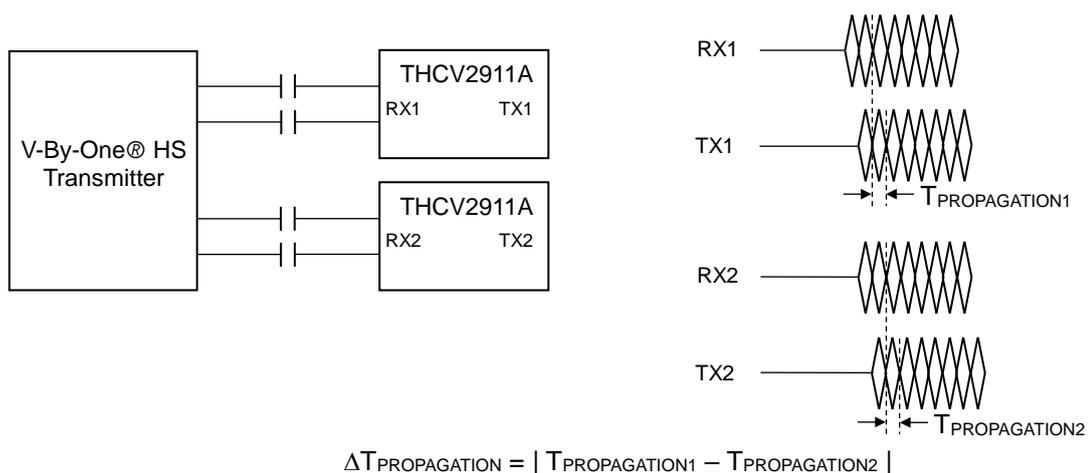
**Table 10. AC Specification**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
T <sub>EN</sub>	Power On to EN High Delay	-	0	-	-	ns
T <sub>ACTIVE</sub>	EN High to Active Delay	-	-	-	200	us
T <sub>PROPAGATION</sub>	Differential Propagation Delay	-	-	150	-	ps
ΔT <sub>PROPAGATION</sub>	Delta Propagation Delay	-	-	-	40	ps



**Figure 5. Power on Sequence**

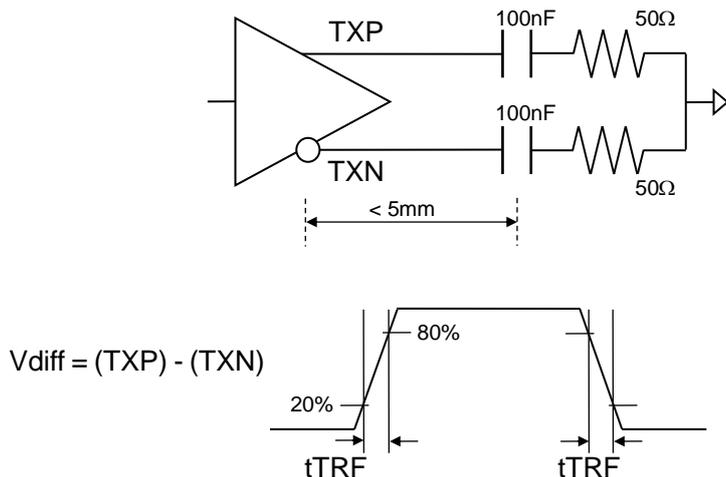


**Figure 6. CML Propagation Delay Timing**

**Table 11. Transmitter AC Specification**

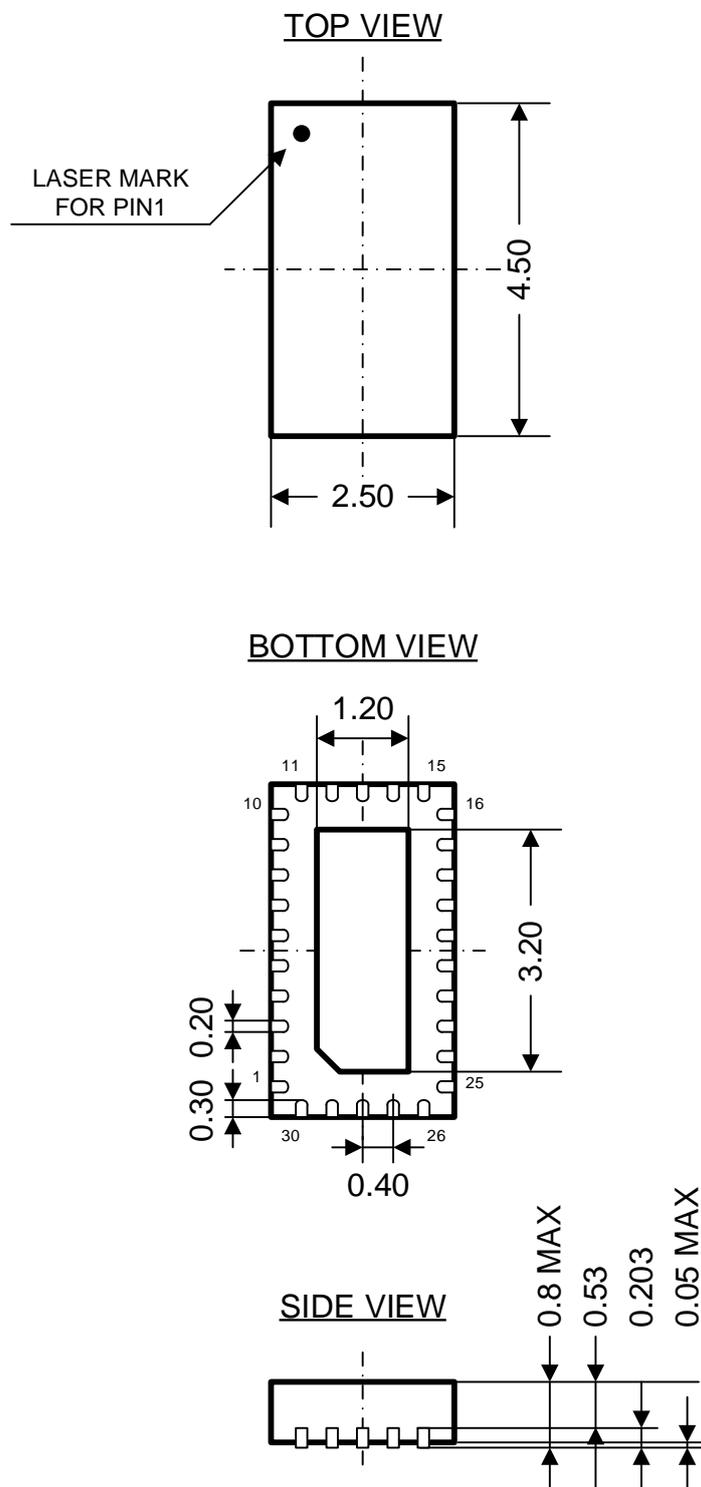
Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
tTRF	Tx Rise/Fall Time	20% to 80 %	50	-	150	ps



**Figure 7. CML Output Switching Timing and Test Circuit**

**Package**



Unit: mm

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10. The product or peripheral parts may be damaged by a surge in voltage over the absolute maximum ratings or malfunction, if pins of the product are shorted by such as foreign substance. The damages may cause a smoking and ignition. Therefore, you are encouraged to implement safety measures by adding protection devices, such as fuses.

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